

100V, 312A, 1.7mΩ N-channel Power SGT MOSFET

JMSH1001NTLQ

Features

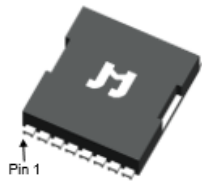
- Ultra-low ON-resistance, R_{DS(ON)}
- Low Gate Charge
- 100% UIS Tested
- 100% ΔV_{ds} Tested
- Halogen-free; RoHS-compliant
- AEC-Q101 Qualified

Applications

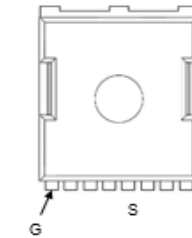
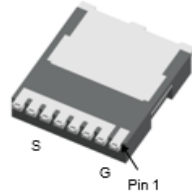
- Load Switch
- PWM Application
- General Automotive Application

Product Summary

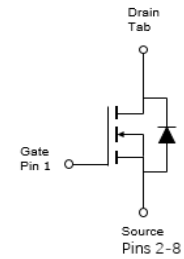
Parameters	Value	Unit
V _{DSS}	100	V
V _{GS(th)_Typ}	2.9	V
I _D (@V _{GS} =10V)	312	A
R _{DS(ON)_Typ} (@V _{GS} =10V)	1.7	mΩ



PowerJE®10x12



Pin Assignment



Schematic Diagram

Ordering Information

Device	Marking	MSL	Form	Package	Reel(pcs)	Per Carton (pcs)
JMSH1001NTLQ-13	SH1001NQ	1	Tape&Reel	PowerJE®10x12	2000	10000

Absolute Maximum Ratings (@ T_C = 25°C unless otherwise specified)

Symbol	Parameter	Value	Unit
V _{DS}	Drain-to-Source Voltage	100	V
V _{GS}	Gate-to-Source Voltage	±20	V
I _D	Continuous Drain Current	T _C = 25°C	312
		T _C = 100°C	221
I _{DM}	Pulsed Drain Current ⁽¹⁾	Refer to Fig.4	A
E _{AS}	Single Pulsed Avalanche Energy ⁽²⁾	1722	mJ
P _D	Power Dissipation	T _C = 25°C	429
		T _C = 100°C	214
T _J , T _{STG}	Junction & Storage Temperature Range	-55 to 175	°C

Thermal Characteristics

Symbol	Parameter	Max	Unit
R _{θJA}	Thermal Resistance, Junction to Ambient ⁽³⁾	33	°C/W
R _{θJC}	Thermal Resistance, Junction to Case	0.35	



**Electrical Characteristics** ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	100	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 80\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.1	2.9	3.8	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽⁴⁾	$V_{GS} = 10\text{V}, I_D = 20\text{A}$	-	1.7	2.2	m Ω
Dynamic Characteristics						
R_g	Gate Resistance	$f = 1\text{MHz}$	-	2.3	-	Ω
C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 50\text{V},$ $f = 1\text{MHz}$	8341	11677	15764	pF
C_{oss}	Output Capacitance		1260	1764	2381	pF
C_{rss}	Reverse Transfer Capacitance		27	38	52	pF
Q_g	Total Gate Charge	$V_{GS} = 0 \text{ to } 10\text{V}$ $V_{DS} = 50\text{V}, I_D = 20\text{A}$	121	169	228	nC
Q_{gs}	Gate Source Charge		39	55	74	nC
Q_{gd}	Gate Drain("Miller") Charge		26	36	49	nC
Switching Characteristics						
$t_{d(on)}$	Turn-On DelayTime	$V_{GS} = 10\text{V}, V_{DD} = 50\text{V}$ $I_D = 20\text{A}, R_{GEN} = 3\Omega$	-	34	-	ns
t_r	Turn-On Rise Time		-	43	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	95	-	ns
t_f	Turn-Off Fall Time		-	51	-	ns
Body Diode Characteristics						
I_S	Maximum Continuous Body Diode Forward Current		-	-	312	A
I_{SM}	Maximum Pulsed Body Diode Forward Current		-	-	1247	A
V_{SD}	Body Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = 20\text{A}$	-		1.2	V
t_{rr}	Body Diode Reverse Recovery Time	$I_F = 15\text{A}, di/dt = 100\text{A}/\mu\text{s}$	74	104	140	ns
Q_{rr}	Body Diode Reverse Recovery Charge		-	350	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting $T_J = 25^\circ\text{C}$, $V_{DD} = 50\text{V}$, $V_G = 10\text{V}$, $R_G = 25\text{ohm}$, $L = 3\text{mH}$, $I_{AS} = 33.88\text{A}$, $V_{DD} = 0\text{V}$ during time in avalanche.
 3. $R_{\theta JA}$ is measured with the device mounted on a 1inch^2 pad of 2oz copper FR4 PCB.
 4. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.



Typical Performance Characteristics

Figure 1: Power De-rating

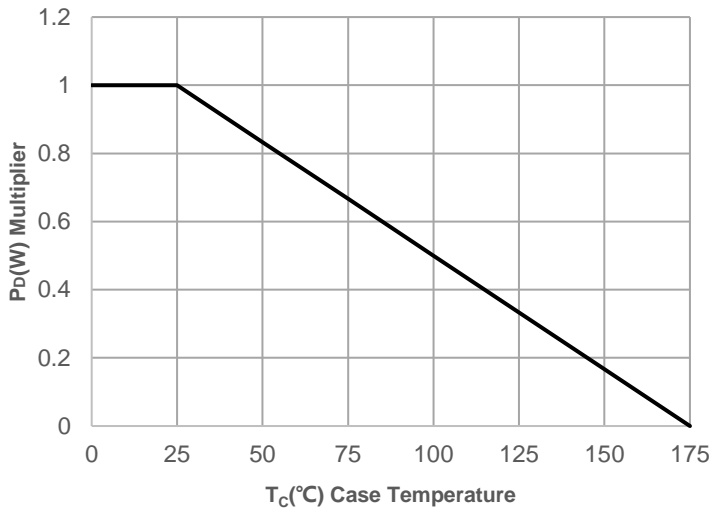


Figure 2: Current De-rating

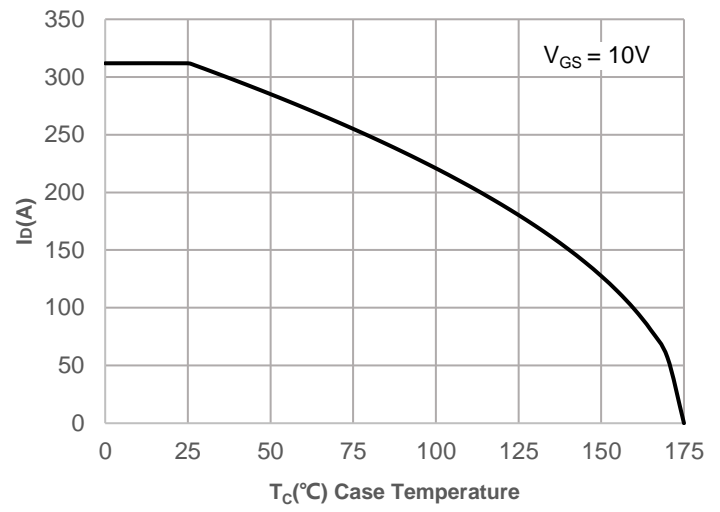


Figure 3: Normalized Maximum Transient Thermal Impedance

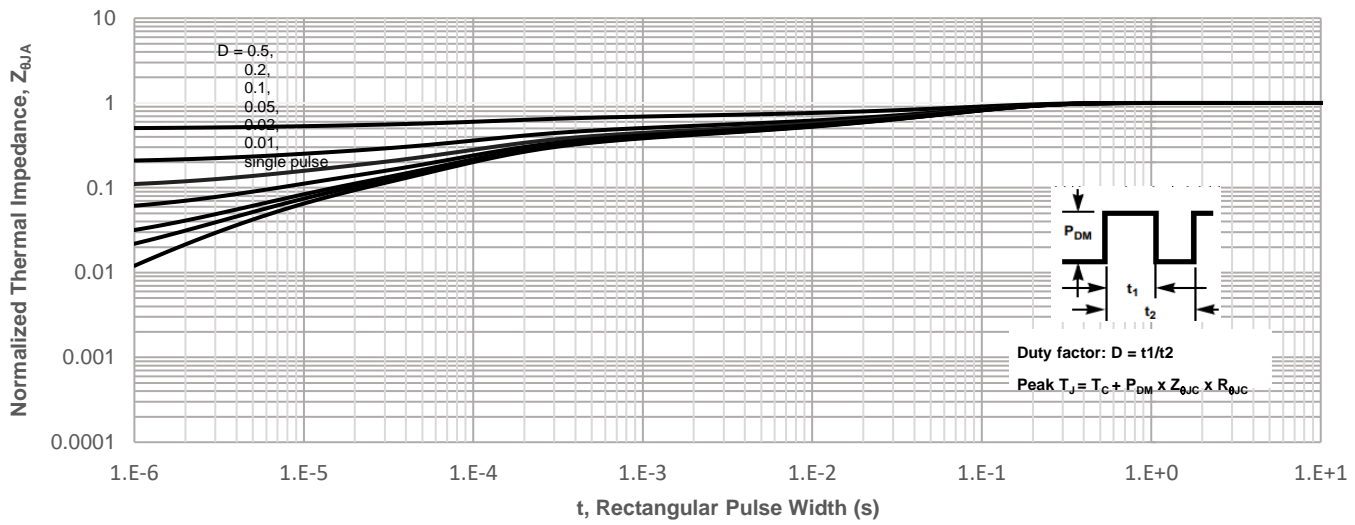
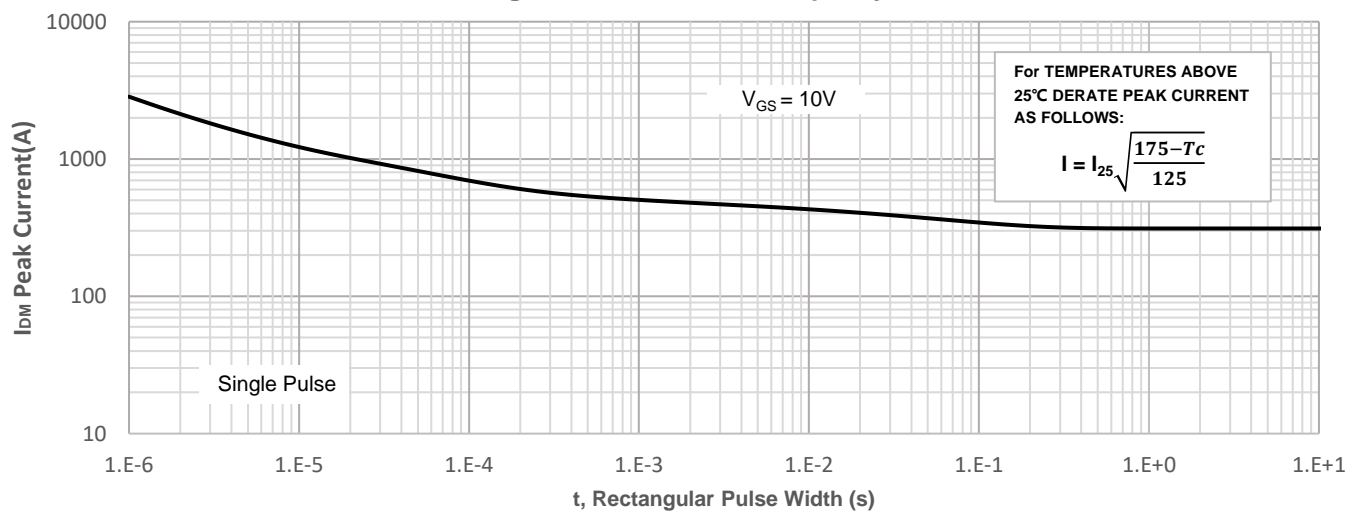


Figure 4: Peak Current Capacity



Typical Performance Characteristics

Figure 5: Output Characteristics

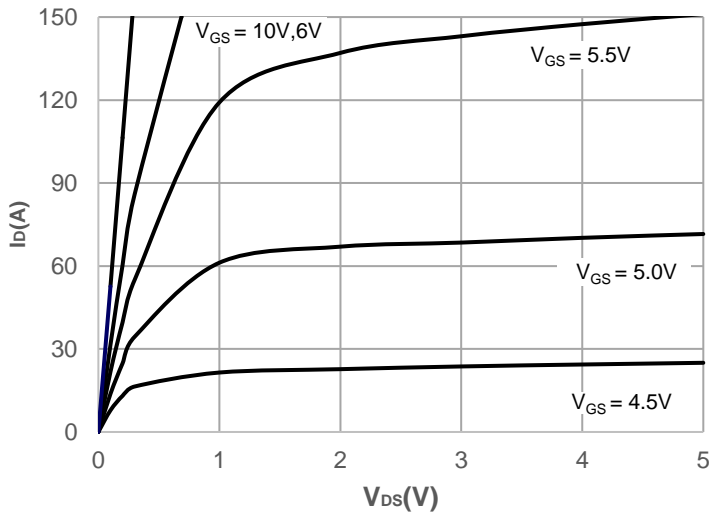


Figure 6: Typical Transfer Characteristics

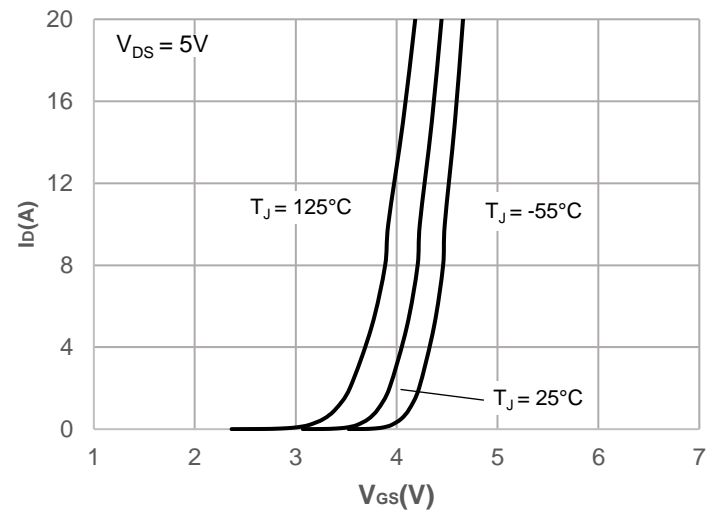


Figure 7: On-resistance vs. Drain Current

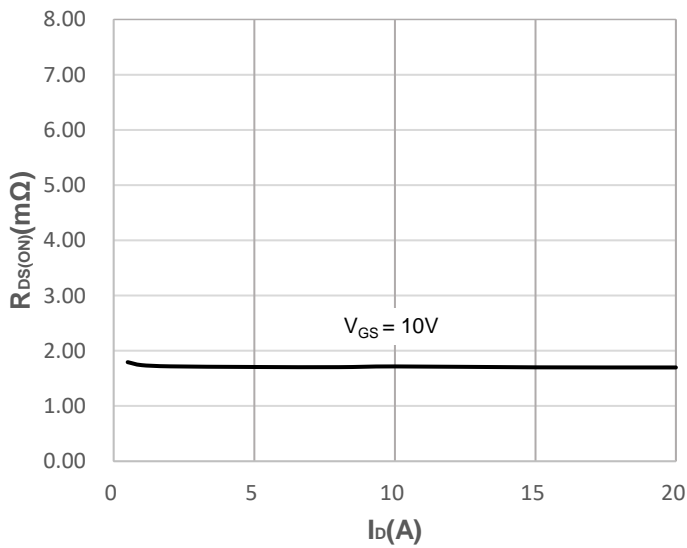


Figure 8: Body Diode Characteristics

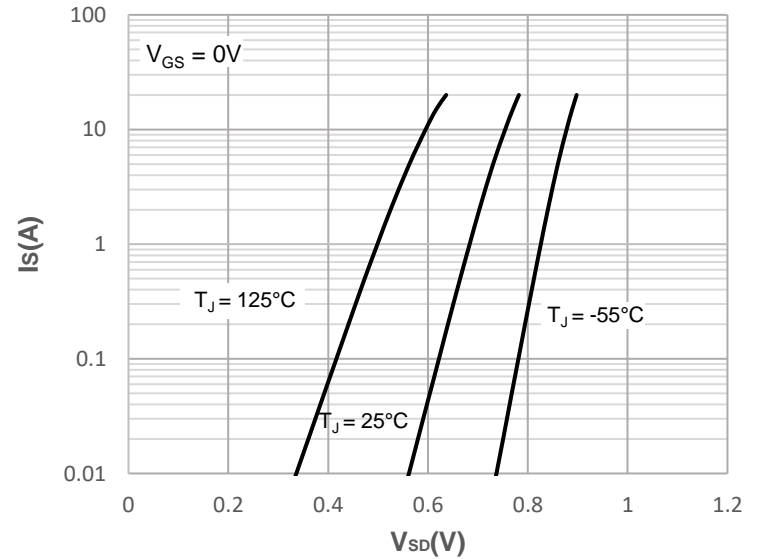


Figure 9: Gate Charge Characteristics

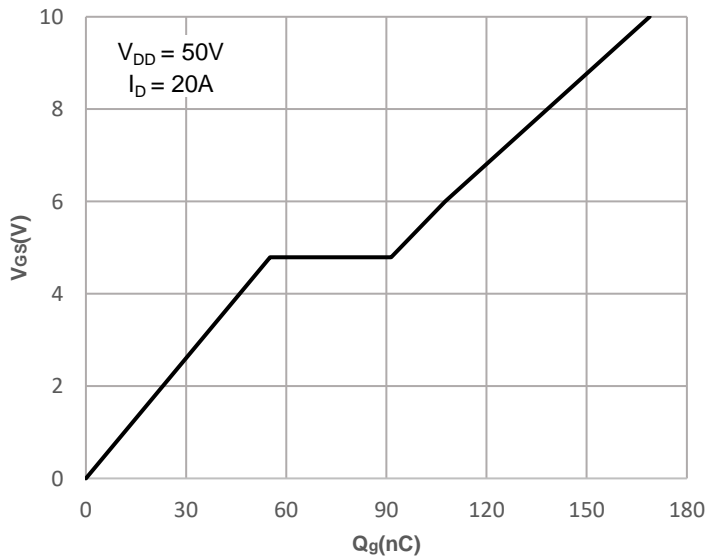
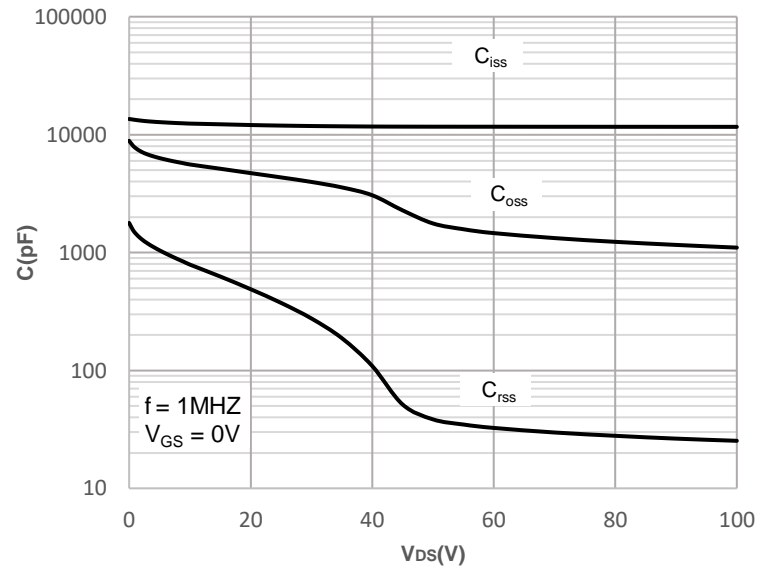


Figure 10: Capacitance Characteristics



Typical Performance Characteristics

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

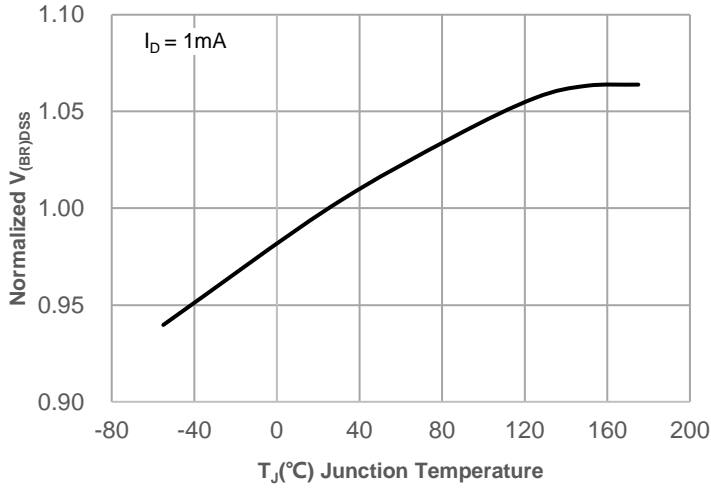


Figure 12: Normalized on Resistance vs. Junction Temperature

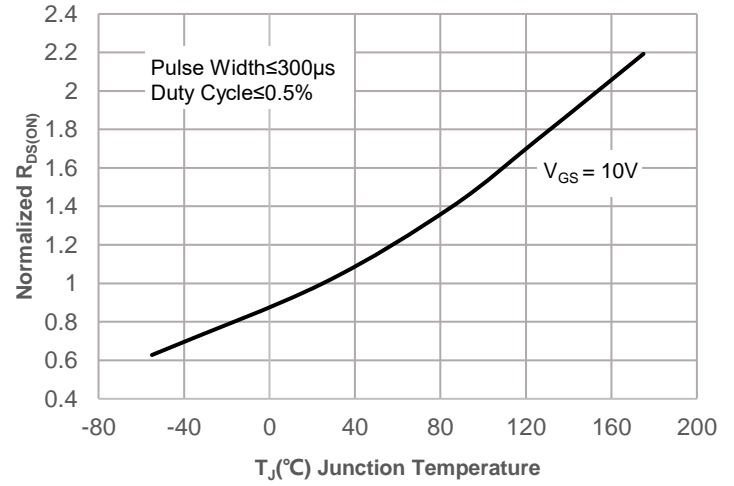


Figure 13: Normalized Threshold Voltage vs. Junction Temperature

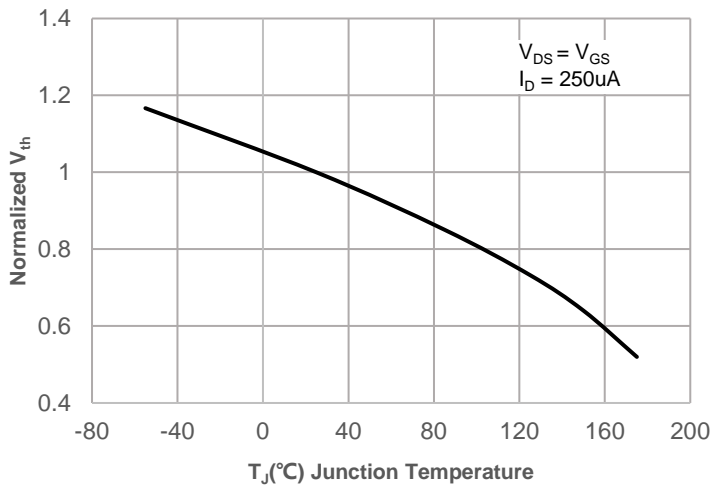


Figure 14: R_DS(ON) vs. V_GS

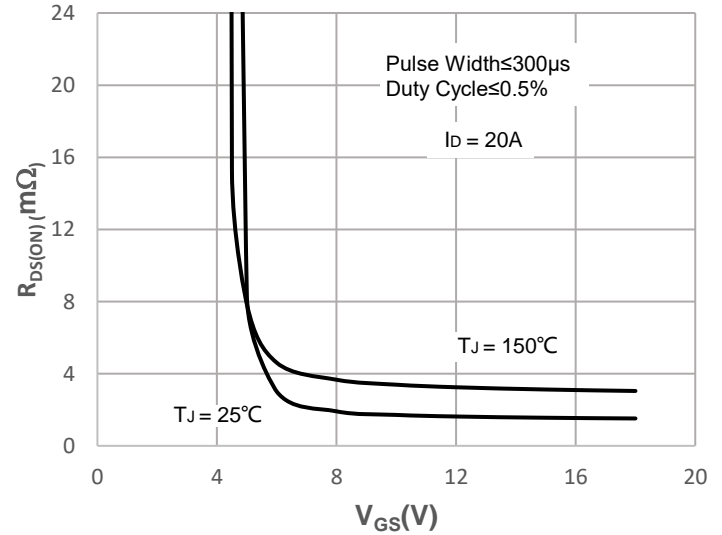
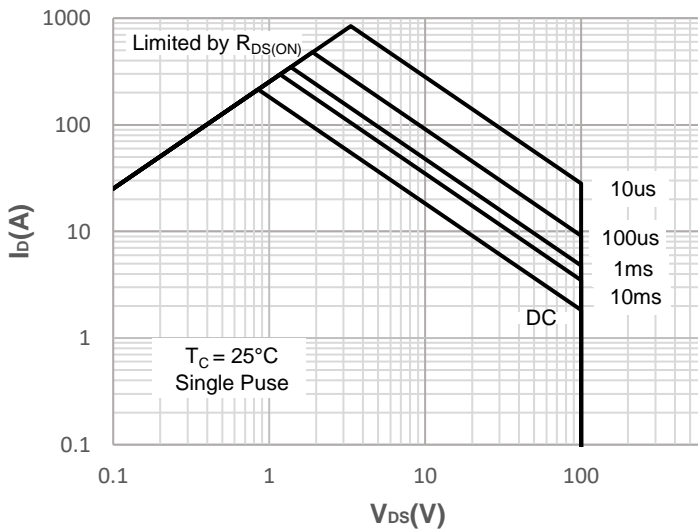


Figure 15: Maximum Safe Operating Area



Test Circuit

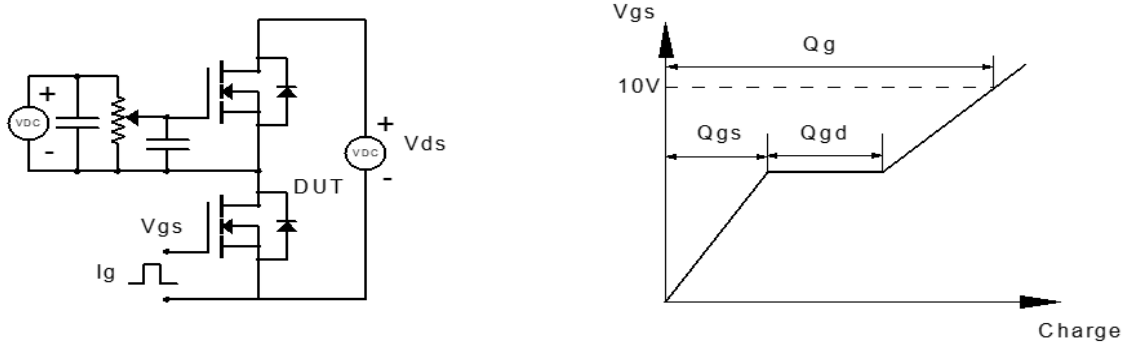


Figure 1: Gate Charge Test Circuit & Waveform

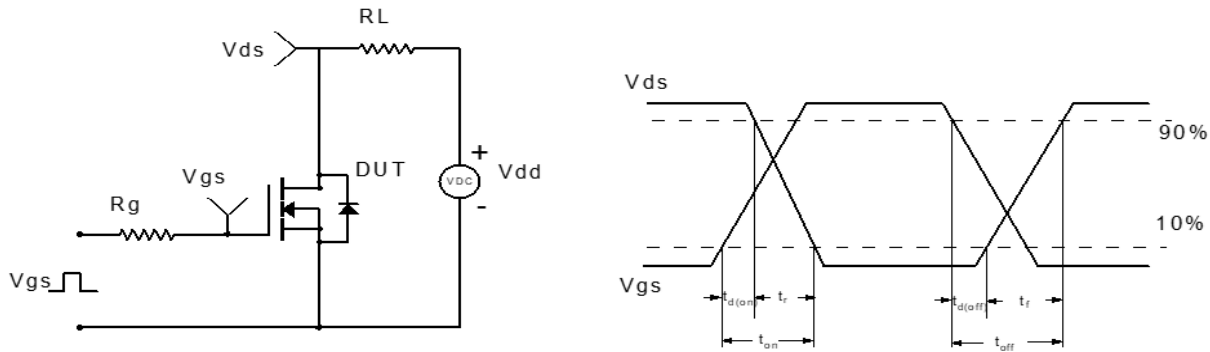


Figure 2: Resistive Switching Test Circuit & Waveform

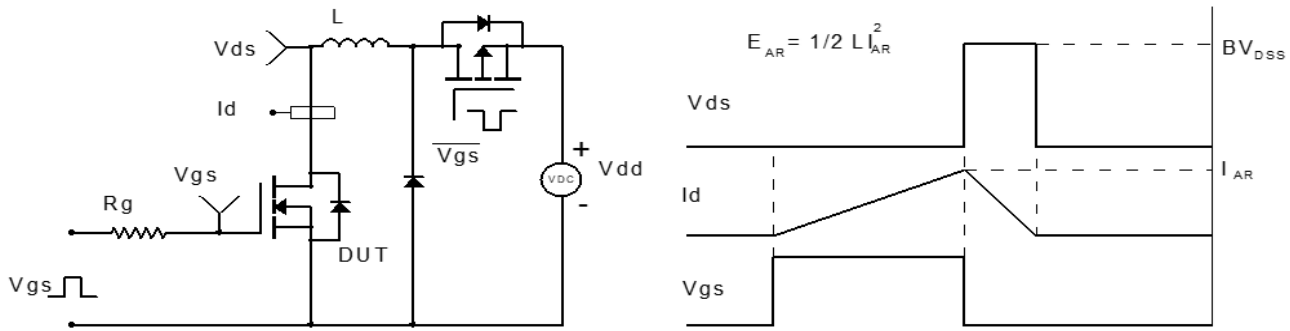


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

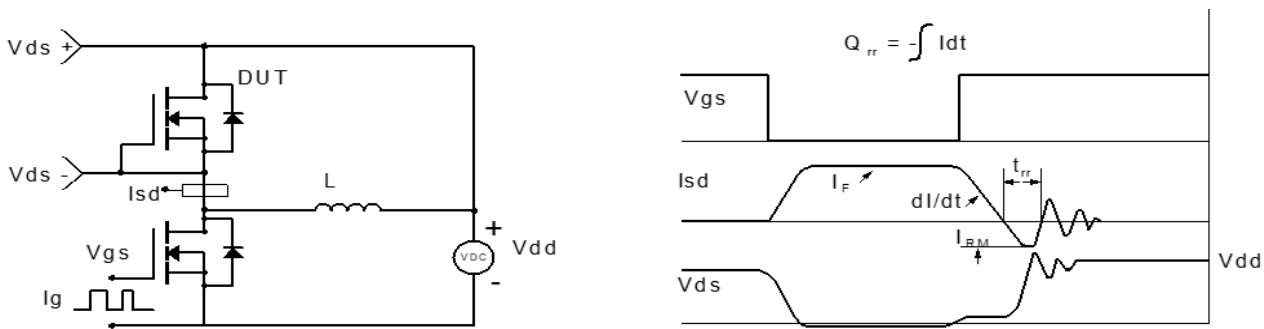
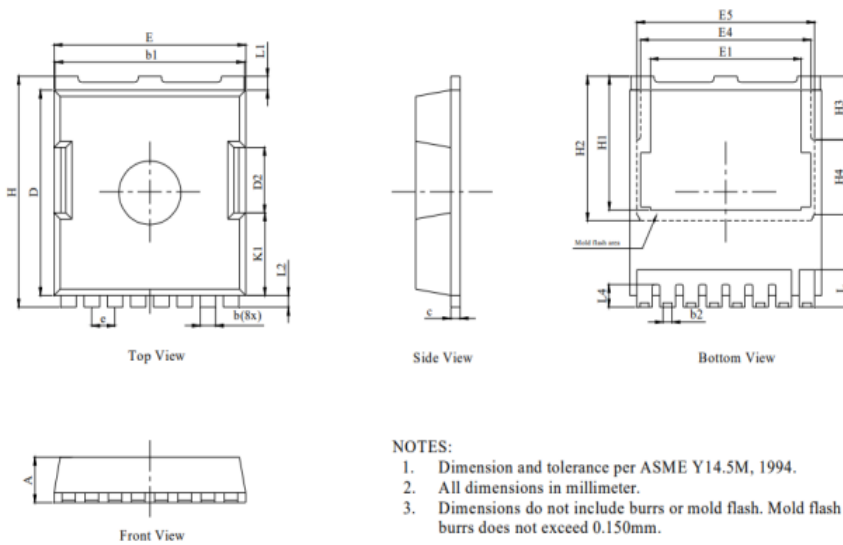


Figure 4: Diode Recovery Test Circuit & Waveform



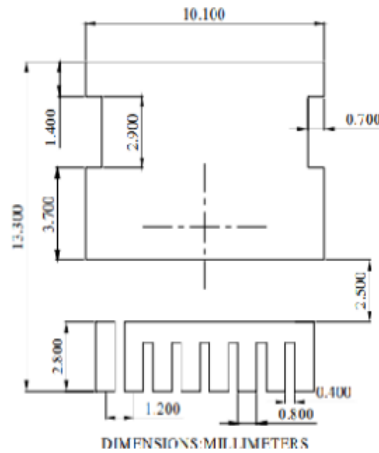
Package Mechanical Data(PowerJE®10x12)

Package Outlines



- NOTES:
1. Dimension and tolerance per ASME Y14.5M, 1994.
 2. All dimensions in millimeter.
 3. Dimensions do not include burrs or mold flash. Mold flash or burrs does not exceed 0.150mm.

Recommended Soldering Footprint



DIM.	MILLIMETER		
	MIN	NOM	MAX
A	2.20	2.30	2.50
b	0.70	0.80	0.90
b1	9.70	9.80	9.90
b2	0.42	0.46	0.50
C	0.40	0.50	0.65
D	10.28	10.38	10.58
D2	3.30		
E	9.70	9.90	10.10
E1	7.80		
E4	8.80		
E5	9.20		
e	1.20(BSC)		
H	11.48	11.68	11.88
H1	6.55	6.75	6.85
H2	7.30		
H3	3.20		
H4	3.80		
K1	4.18		
L	1.70	1.90	2.10
L1	0.70		
L2	0.60		
L4	1.00	1.15	1.30

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